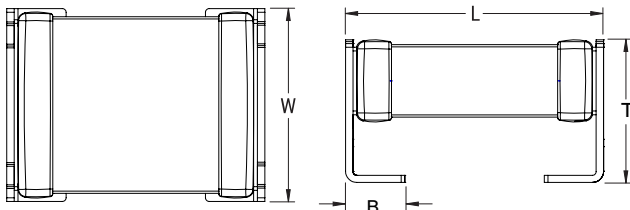


TOP VIEW
Single or Double Chip Stack

PROFILE VIEW
Single Chip Stack



Click [here](#) for the 3D model.

General Information

| | |
|--------------------------|---|
| Series | KPS SMD Comm X8L HT150C |
| Style | Stacked Chip |
| Description | SMD, MLCC, Stacked, Single Chip, High Temperature |
| Features | High Temperature |
| RoHS | Yes |
| Termination | Tin |
| AEC-Q200 | No |
| Typical Component Weight | 160 mg |
| Chip Size | 1210-1 |
| Shelf Life | 78 Weeks |
| MSL | 1 |

Specifications

| | |
|--|---|
| Capacitance | 1 uF |
| Measurement Condition | 1 kHz 1.0Vrms |
| Tolerance | 20% |
| Voltage DC | 50 VDC |
| Dielectric Withstanding Voltage | 125 VDC |
| Temperature Range | -55/+150°C |
| Temp. Coefficient | X8L |
| Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC) | +15% (-55C to +125C), +15/-40% (125C to 150C), 1kHz 1.0Vrms |
| Dissipation Factor | 2.5% 1 kHz 1.0Vrms |
| Aging Rate | 3% Loss/Decade Hour: Referee Time is 1000 Hours |
| Insulation Resistance | 500 MOhms |

Dimensions

| | |
|---|------------------|
| L | 3.5mm +/-0.3mm |
| W | 2.6mm +/-0.3mm |
| T | 3.35mm +/-0.10mm |
| B | 0.8mm +/-0.15mm |

Packaging Specifications

| | |
|--------------------|--------------------------|
| Packaging | T&R, 180mm, Plastic Tape |
| Packaging Quantity | 600 |

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitute - and we specifically disclaim - any warranty concerning suitability for a specific customer application or use. This Information is intended for use only by customers who have the requisite experience and capability to determine the correct products for their application. Any technical advice inferred from this Information or otherwise provided by us with reference to the use of our products is given gratis, and we assume no obligation or liability for the advice given or results obtained.